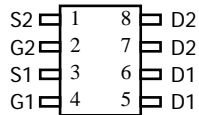
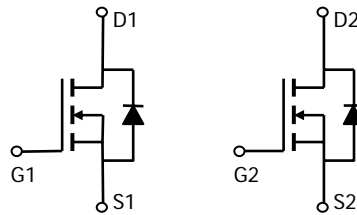


4812
Dual N-Channel Enhancement Mode Field Effect Transistor
General Description

The 4812 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The two MOSFETs make a compact and efficient switch and synchronous rectifier combination for use in buck converters. *4812 is Pb-free (meets ROHS & Sony 259 specifications). 4812 is a Green Product ordering option. 4812 is electrically identical.*

Features

$V_{DS} (V) = 30V$
 $I_D = 8.0A (V_{GS} = 10V)$
 $R_{DS(ON)} < 22m\Omega (V_{GS} = 10V)$
 $R_{DS(ON)} < 34m\Omega (V_{GS} = 4.5V)$


SOIC-8

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^A	I_D	$T_A=25^\circ C$	8.0
Pulsed Drain Current ^B	I_{DM}	30	A
Power Dissipation	P_D	$T_A=25^\circ C$	2
		$T_A=70^\circ C$	1.44
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	$t \leq 10s$	48	$^\circ C/W$
Maximum Junction-to-Ambient ^A		Steady-State	74	$^\circ C/W$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	35	40	$^\circ C/W$



Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V			±50	nA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.3		2.0	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	20			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =8.0A		23	28	mΩ
		V _{GS} =4.5V, I _D =5.6A		37	42	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =6.9A	10	15.4		S
V _{SD}	Diode Forward Voltage	I _S =1A		0.76	1	V
I _S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		680	820	pF
C _{oss}	Output Capacitance			102		pF
C _{riss}	Reverse Transfer Capacitance			77		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		3	3.6	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =6.9A		13.84	17	nC
Q _{g(4.5V)}	Total Gate Charge			6.74	8.1	nC
Q _{gs}	Gate Source Charge			1.82		nC
Q _{gd}	Gate Drain Charge			3.2		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =2.2Ω, R _{GEN} =3Ω		4.6	7	ns
t _r	Turn-On Rise Time			4.1	6.2	ns
t _{D(off)}	Turn-Off DelayTime			20.6	30	ns
t _f	Turn-Off Fall Time			5.2	7.5	ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =6.9A, di/dt=100A/μs		16.5	20	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =6.9A, di/dt=100A/μs		7.8	10	nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

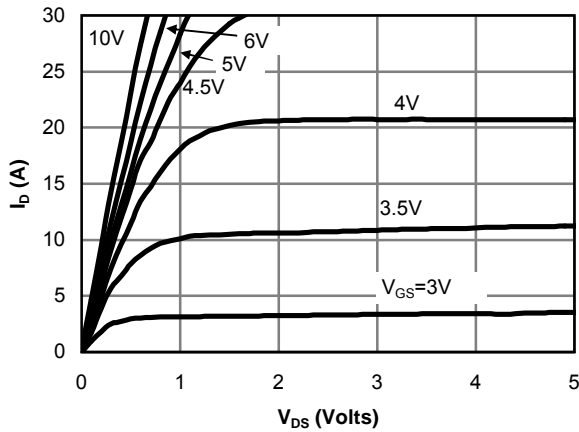


Fig 1: On-Region Characteristics

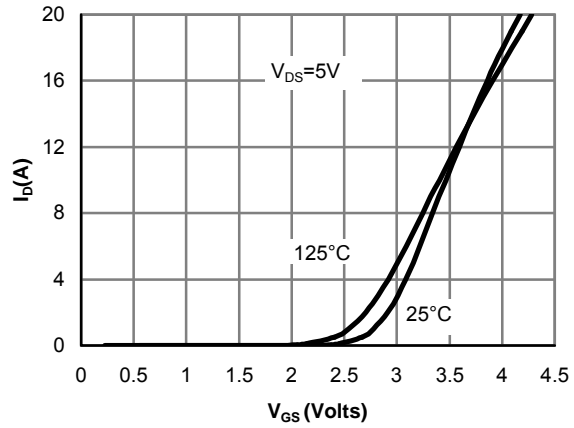


Figure 2: Transfer Characteristics

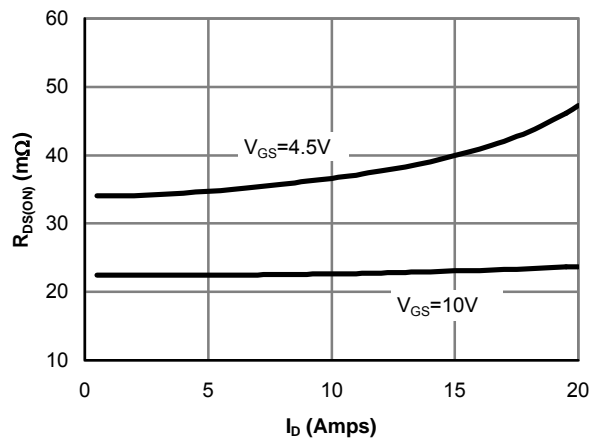


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

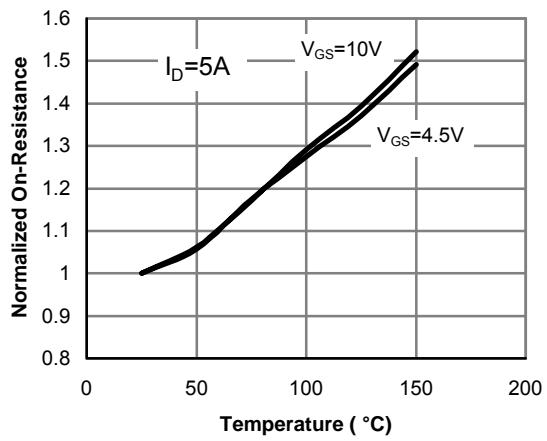


Figure 4: On-Resistance vs. Junction Temperature

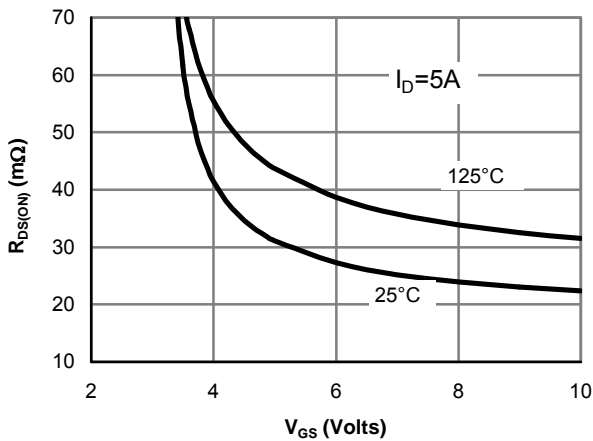


Figure 5: On-Resistance vs. Gate-Source Voltage

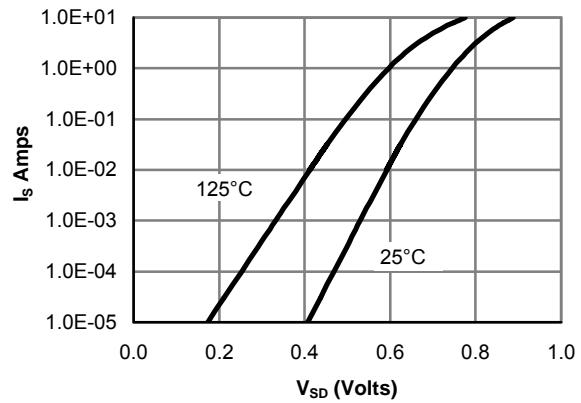


Figure 6: Body diode characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

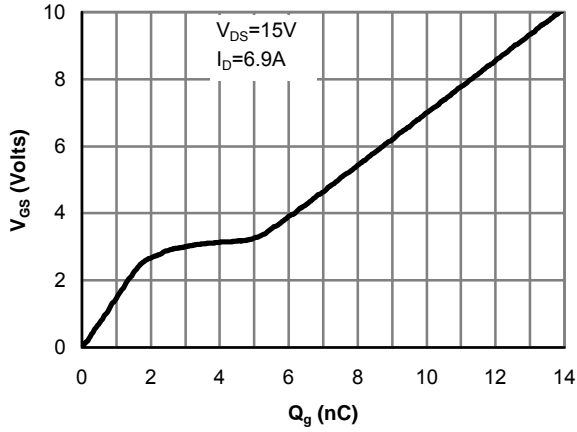


Figure 7: Gate-Charge characteristics

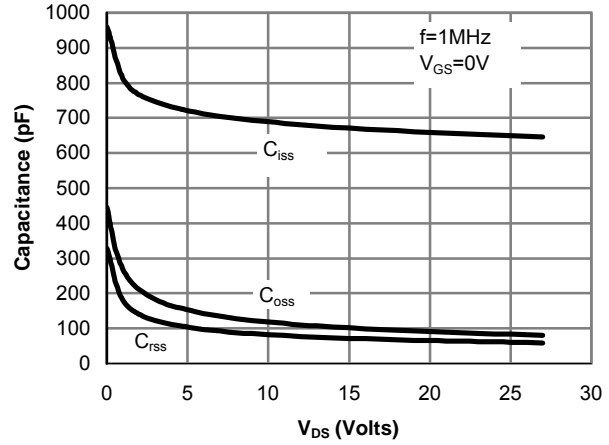


Figure 8: Capacitance Characteristics

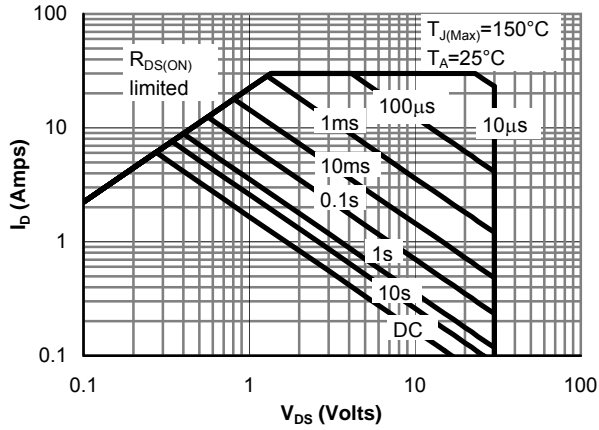


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

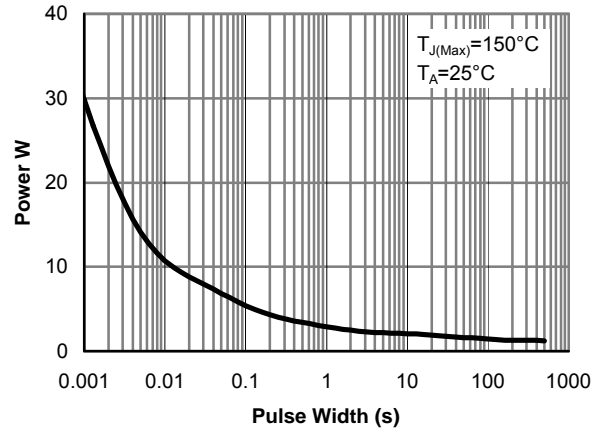


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

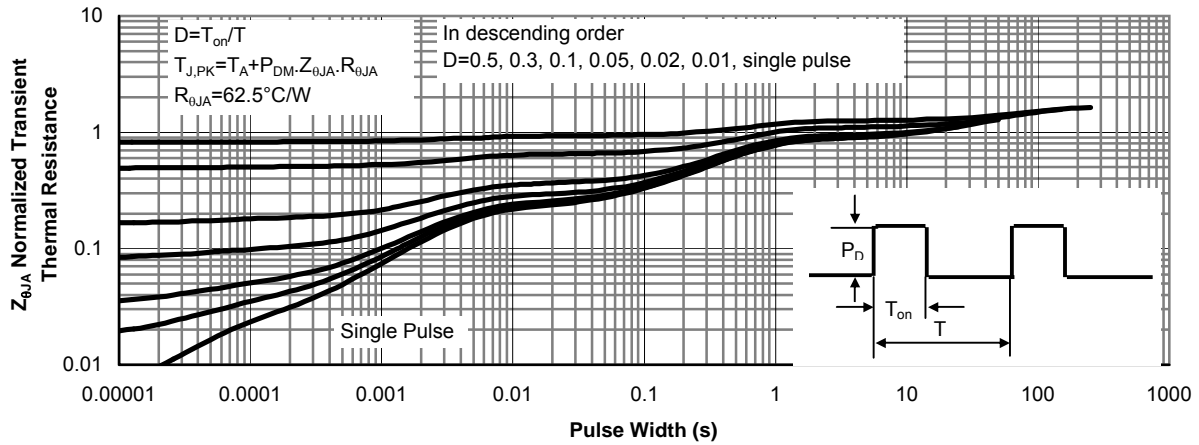


Figure 11: Normalized Maximum Transient Thermal Impedance